



## Final Product Change Notification

202102025F01 : Smart Power SO8 and SO16 Capacity Expansion from ASEN to ATBK

**Note:** This notice is NXP Company Proprietary.

**Issue Date:** Apr 01, 2021 **Effective date:** Jun 30, 2021

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### Management summary

Capacity expansion for SO8 and SO16 in the mainstream Cu-wire technology in our internal assembly facility in Bangkok.

### Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input checked="" type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input checked="" type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

## PCN Overview

### Description

Add assembly and test capacity in SO8 (SOT96) and SO16 (SOT109) next to ASEN also in ATBK combined with Cu-wire introduction.

ASEN will continue assembling in Gold wire.

Full traceability available on the origin of products via packing, packing label and assembly date code.

For TEA2016AAT/1/S30 and TEA2016AATH1/1/S30 only: change MSL level from MSL 1 to MSL 3 (shelf life change only).

### Reason

In view of increased demand for Smart Power products and semiconductors in particular, we have qualified a second source for a part of our product portfolio being our internal assembly fab in Bangkok Thailand.

Additional benefit of qualifying an internal industrial facility is that we are able to deal with fluctuations in customer demand having a more reliable commitment on production capacity needed. In the light of standardization and process- and capacity optimization, we qualified the main stream Cu wire technology and related bill of material for products concerned.

### Identification of Affected Products

Top Side Marking

ASEN and ATBK use identical Marking blank

Line 1, no changes: marking will be the same for both ASEN as ATBK

Line 2, no changes: Diffusion lot number / batch ID + Assembly sequence ID of Die

Line 3: assembly location indicator "X" or ASEN and "n" for ATBK

Line 3 coding: Manufacturing code to NX3-00130 (Traceability requirements) + RoHS indicator + Date code + Mask version + Release status code

Line 3 examples:

ASEN: rXDywwn, "X" is ASEN location

ATBK: rnDywwn, "n" is ATBK location

## Product Availability

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### Sample Information

Samples are available upon request

### Production

Planned first shipment Jun 30, 2021

## Anticipated Impact on Form, Fit, Function, Reliability or Quality

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No Impact on form, fit, function, reliability or quality

### Data Sheet Revision

No impact to existing datasheet

### Disposition of Old Products

Existing inventory will be shipped until depleted

## Timing and Logistics

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In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by May 01, 2021.

## Remarks

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PCN abbreviations:

- ASE: Assembly site ASE, Suzhou China
- ASID: Assembly sequence ID of die
- ATBK: NXP Assembly and Test site Bangkok, Thailand
- ATE: Automated Test Equipment
- ATKH: NXP Assembly and Test site Kaohsiung, Taiwan
- ConAna: construction analysis
- DBID: Diffusion lot number / Batch ID
- Effective date: date after which NXP can start delivering the updated products according to the involved PCN
- ESD-CDM: Electrical Discharge Charged Device Model
- ESD-HBM: Electrical Discharge Human Body Model
- FPCN: Final Product Change Notification
- HTOL: reliability test method, high-temperature operating life
- ICN8: NXP Semiconductors ICN8 Nijmegen, The Netherlands
- MSL: Moisture Sensitivity Level
- MSLA: Moisture Sensitivity Level Assessment
- PCN: Product Change Notification
- PCON / PC: Preconditioning
- PQIP: Product Quality Information Package

- RoHS: Restriction of Hazardous Substances
- SSMC: Systems on Silicon Manufacturing Co, waferfab, Singapore
- TC / TMCL: reliability test method, temperature cycling
- THB: reliability test method, temperature, humidity, bias
- UHST: reliability test method, unbiased highly accelerated stress test
- VIS: Vanguard International Semiconductor Corporation waferfab, Hsinchu Taiwan
- WiDi: Wiring Diagram

## Contact and Support

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NXP Quality Management Team.

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### Affected OPN

TEA19161T/2Y  
TEA19161CT/1Y  
TEA19162T/2J  
TEA19162T/3J  
TEA19162HT/2J  
TEA19162CT/1J  
TEA2095T/1J  
TEA1795T/N1,118  
TEA1995T/1J  
TEA2016AAT/1/S30Y  
TEA2016AAT H1/1/SY